



Brief Datasheet

Ultra-low Power Bluetooth Audio Platform for TWS Applications with Hybrid ANC

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CPU Subsystem	Dual-core STAR-MC1
Memory and Storage	Shared 512 KB SRAM
	Flash in package
	boot ROM
Bluetooth Subsystem	Dual-mode BT 5.3
Audio & Voice Features	2x DACs
	2x ADCs
Peripheral Interfaces	GPADC/GPIO/I2S/TDM/SPI/I2C/UART/DMIC/PWM/.....
Package	50-pin QFN

* The content in the table is subject to change without notice.